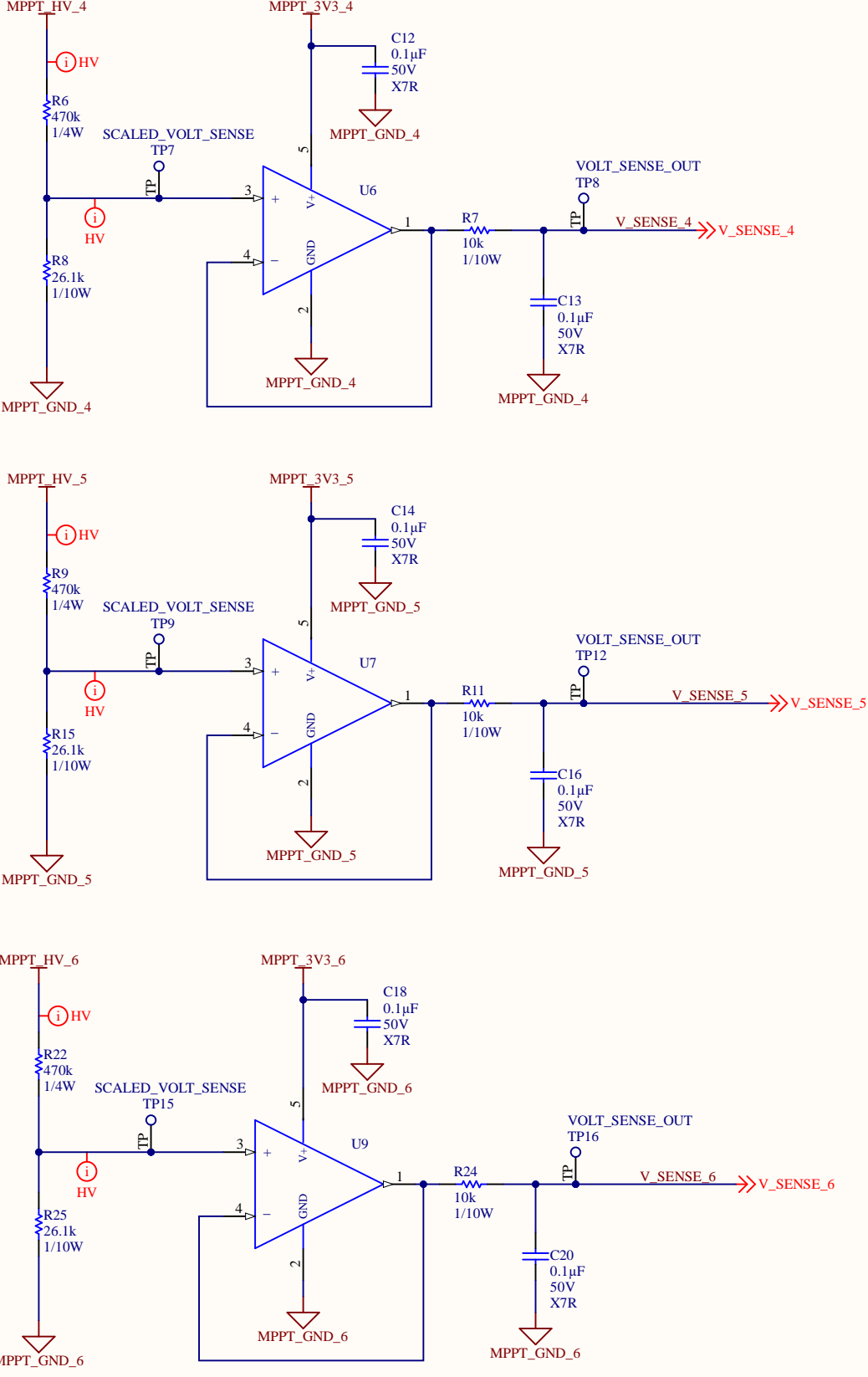
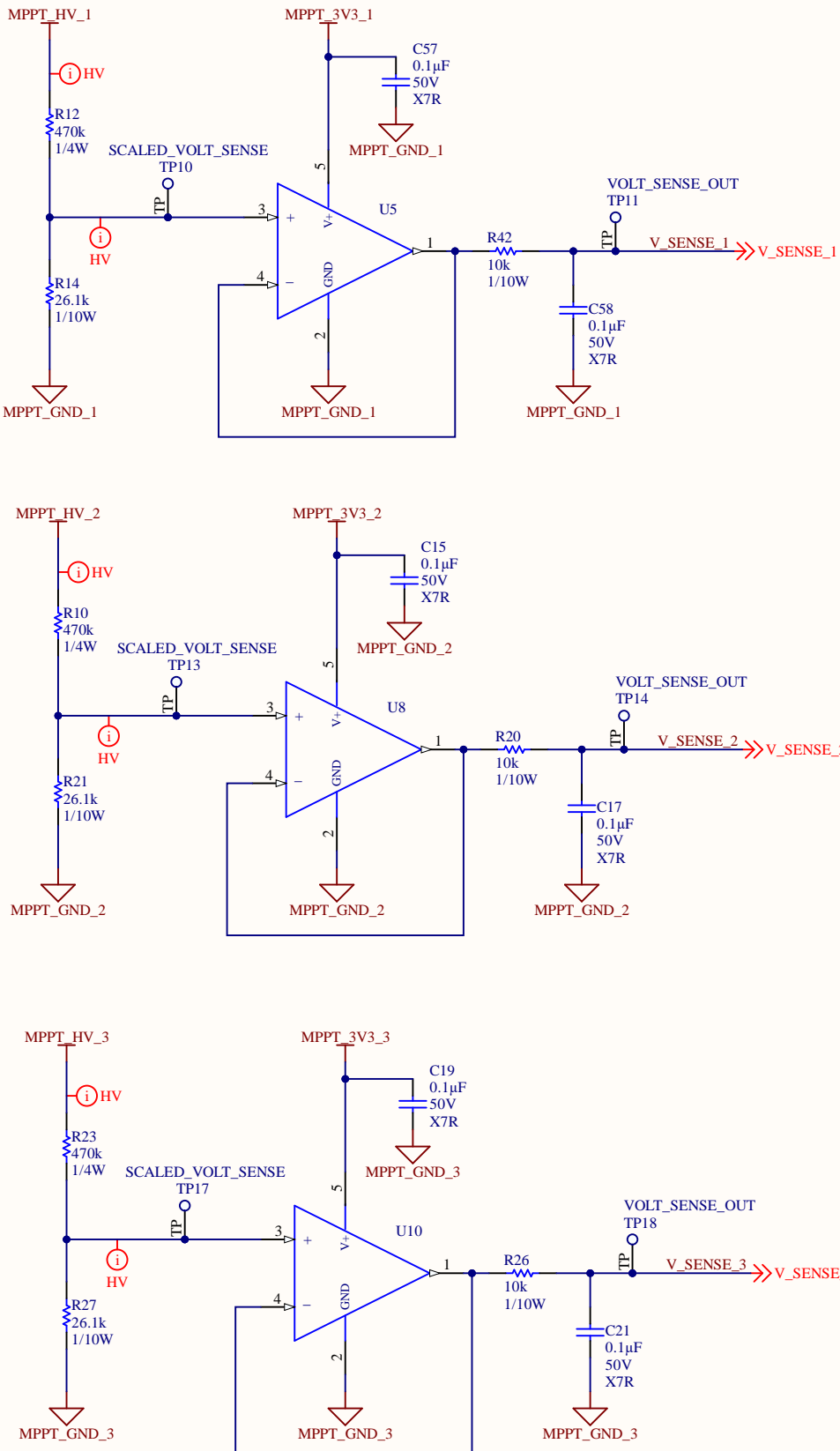
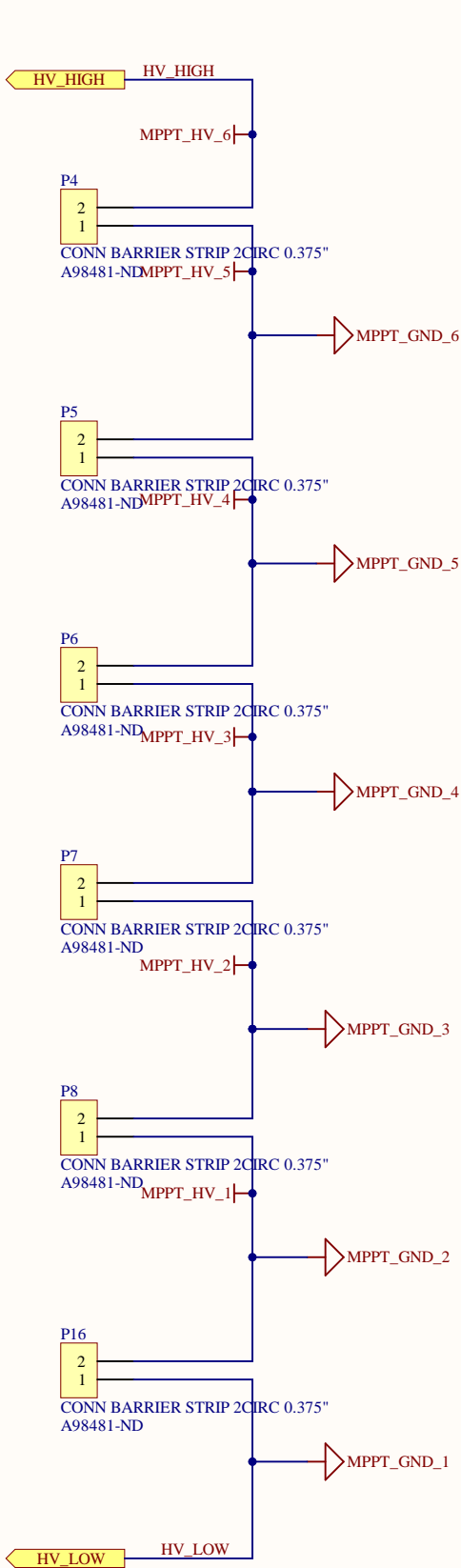
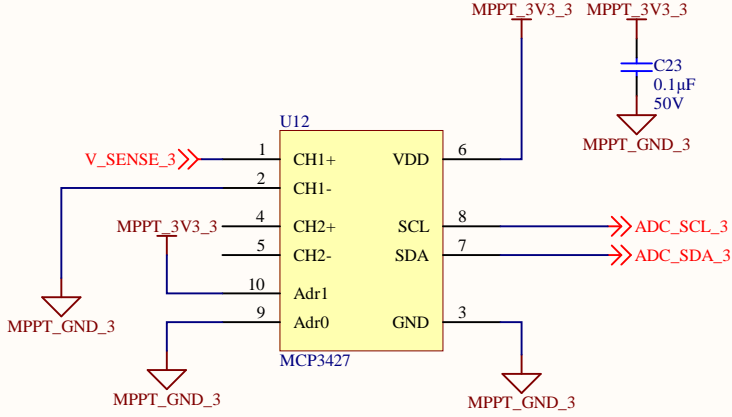
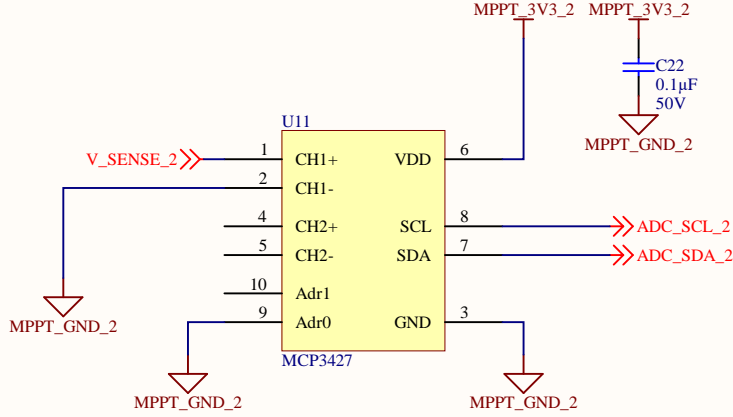
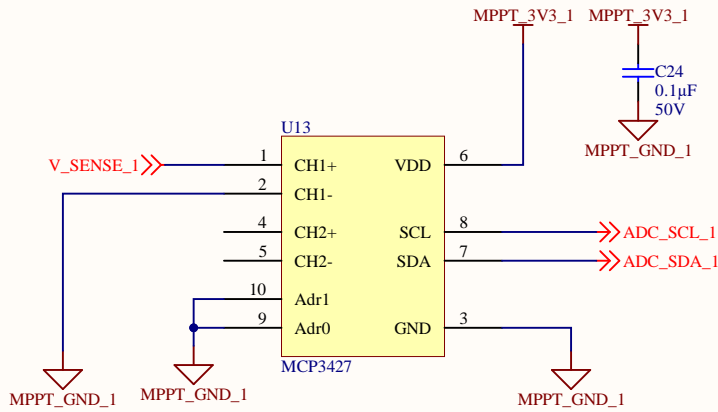


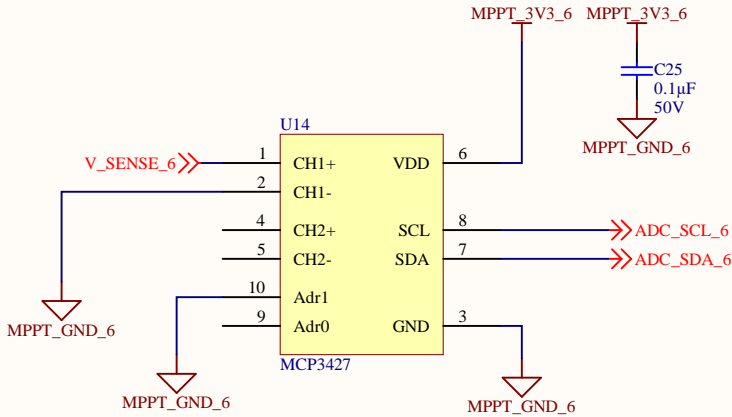
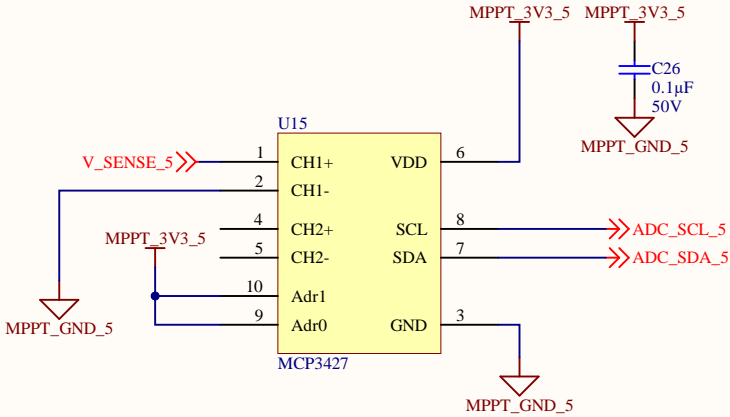
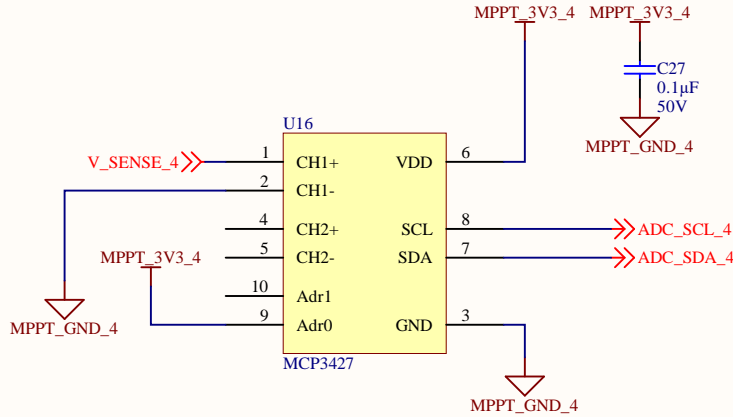
Voltage Sense





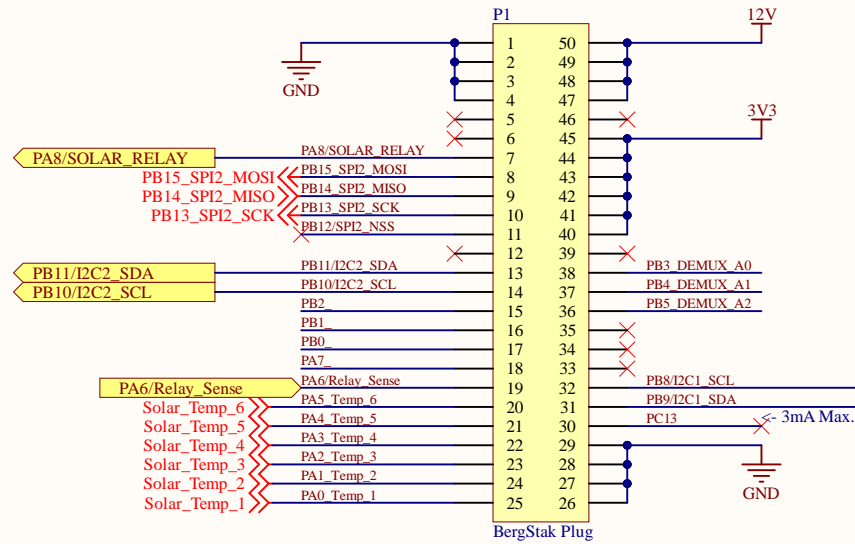
ADCs

I ² C Device Address Bits			Logic Status of Address Selection Pins	
A2	A1	A0	Adr0 Pin	Adr1 Pin
0	0	0	0 (Addr_Low)	0 (Addr_Low)
0	0	1	0 (Addr_Low)	Float
0	1	0	0 (Addr_Low)	1 (Addr_High)
1	0	0	1 (Addr_High)	0 (Addr_Low)
1	0	1	1 (Addr_High)	Float
1	1	0	1 (Addr_High)	1 (Addr_High)
0	1	1	Float	0 (Addr_Low)
1	1	1	Float	1 (Addr_High)
0	0	0	Float	Float

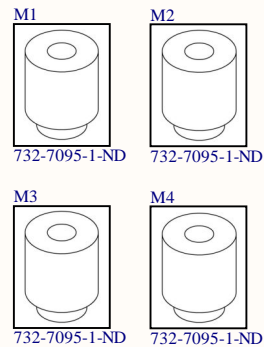


Make combination of pulled high, low and floating (for address pins)

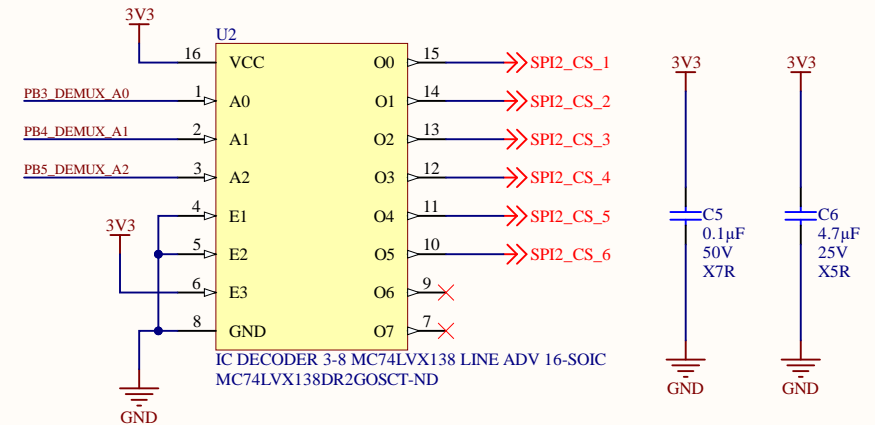
Controller Board




Standoffs



Solar Sense Rev 1.0
MSXIV LOGO
MSXIV LOGO



Project: <i>MSXIV_SolarSense.PrjPcb</i>		<div>MIDNIGHTSUN</div>
Title: *		
Project Author: Aashmika Mali		University of Waterloo 200 University Ave W Waterloo, ON, Canada N2L 3E9
Size: Letter	Revision: 1.0	
Date: 2020-02-23	Sheet * of *	
		Website: www.uwmidsun.com

Passthrough - Current Sense, Fuse, and Relay

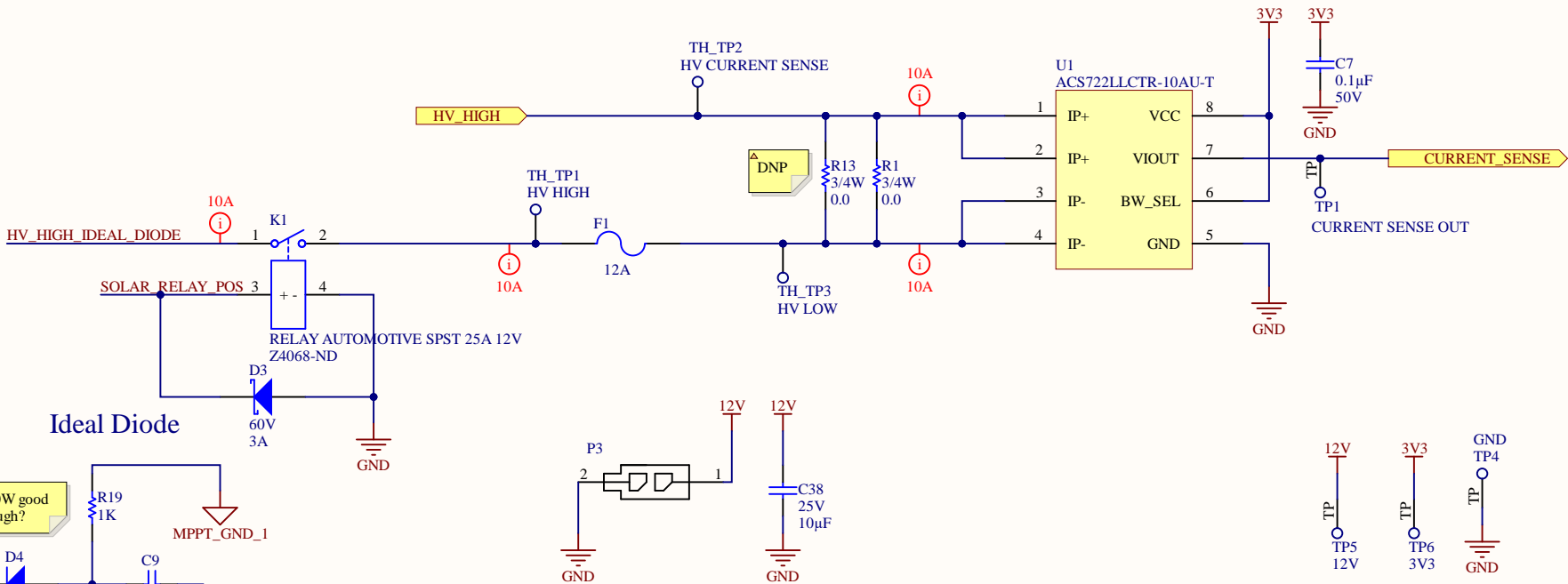
CONN BARRIER STRIP 2CIRC 0.375"



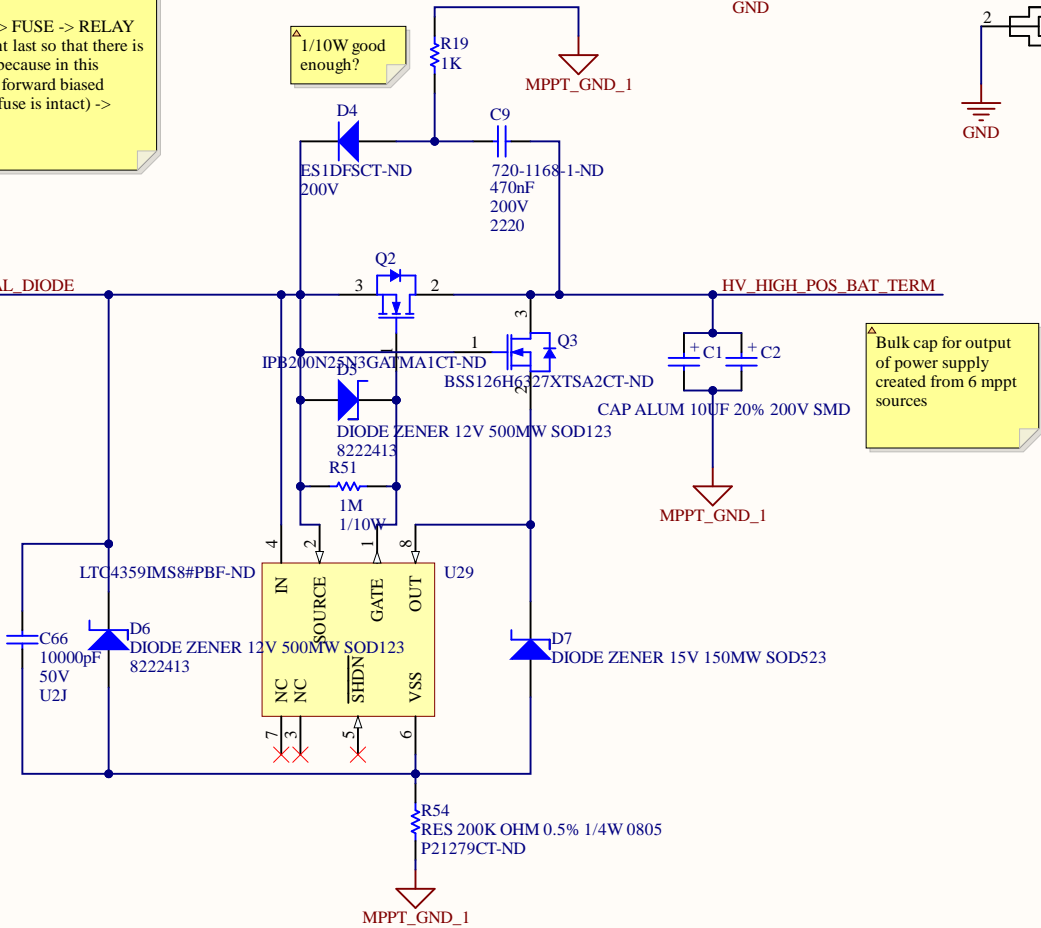
A98481-ND

Pin2: Goes to the negative side of the battery pack
Pin1: Goes to the positive terminal of the battery pack
Note: the trace width for 15A and 170mm of length is 6.5mm

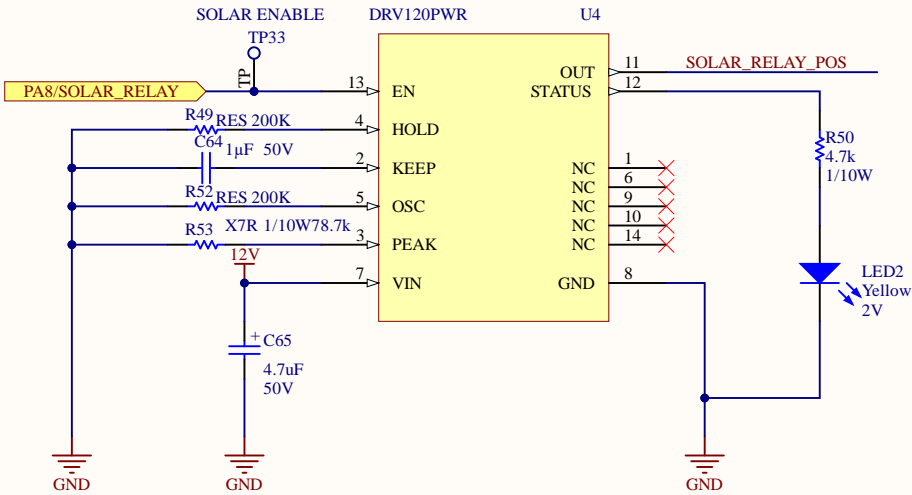
Power Path:
MPPT OUT -> CURRENT SNS -> FUSE -> RELAY
-> IDEAL DIODE (this component last so that there is no current from battery to mppts because in this position the ideal diode cannot be forward biased unless the relay is closed and the fuse is intact) -> BATT TERMS



Ideal Diode



Relay coil low current driver



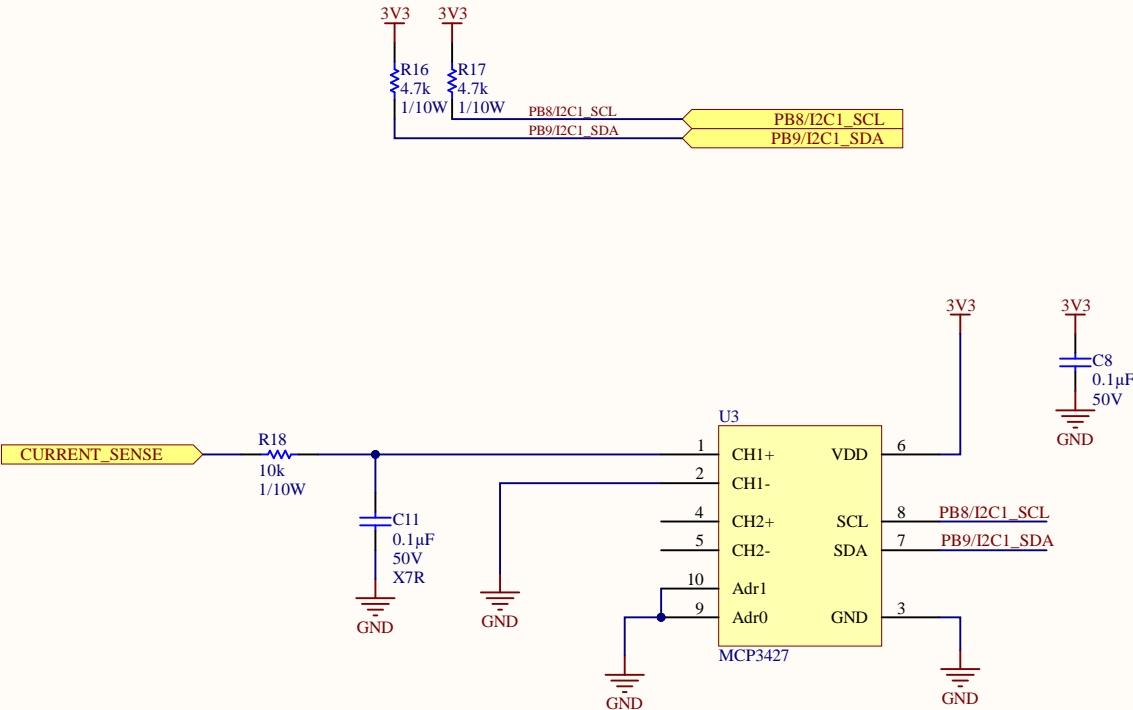
PROJECT	MSXIV_SolarSense.PrjPcb		
DOCUMENT	*		
PART NUMBER	VARIANT	[No Variations]	
DRAWN BY	Aashmika Mali	REVISION	1.0
LAST MODIFIED	2020-02-23	SHEET	* OF *

MIDNIGHT

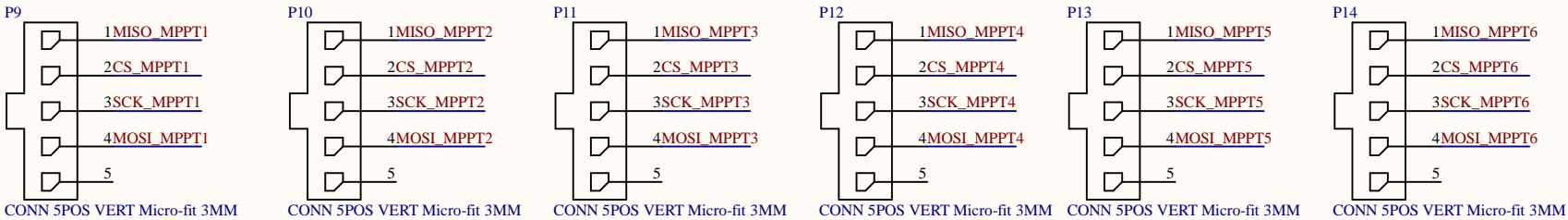
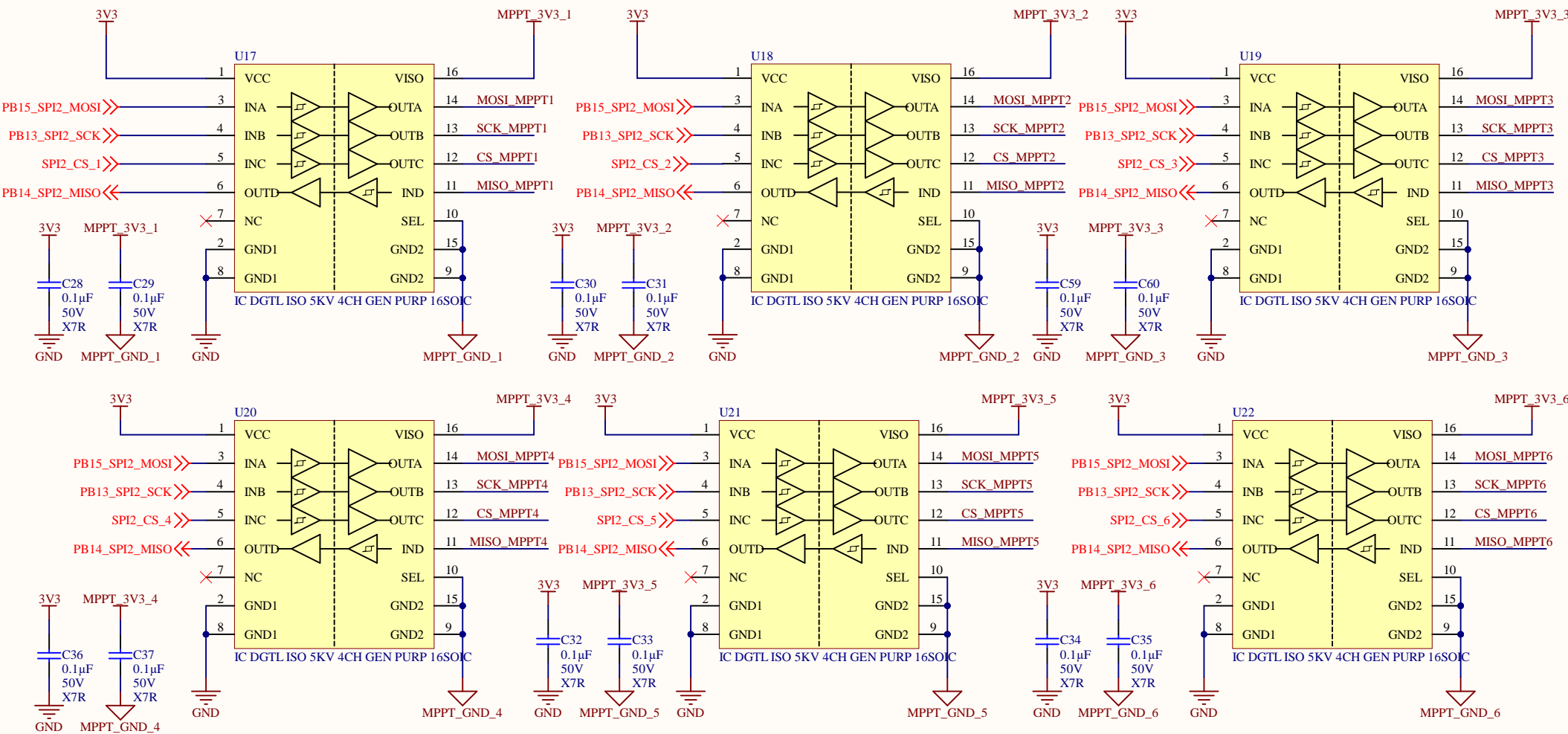
SUN

Engineering 5 - 1002
University of Waterloo
(519) 888-4567 x32978
hardware@uwmidsun.com

I2C Interface (for Current Sense)



SPI Isolators



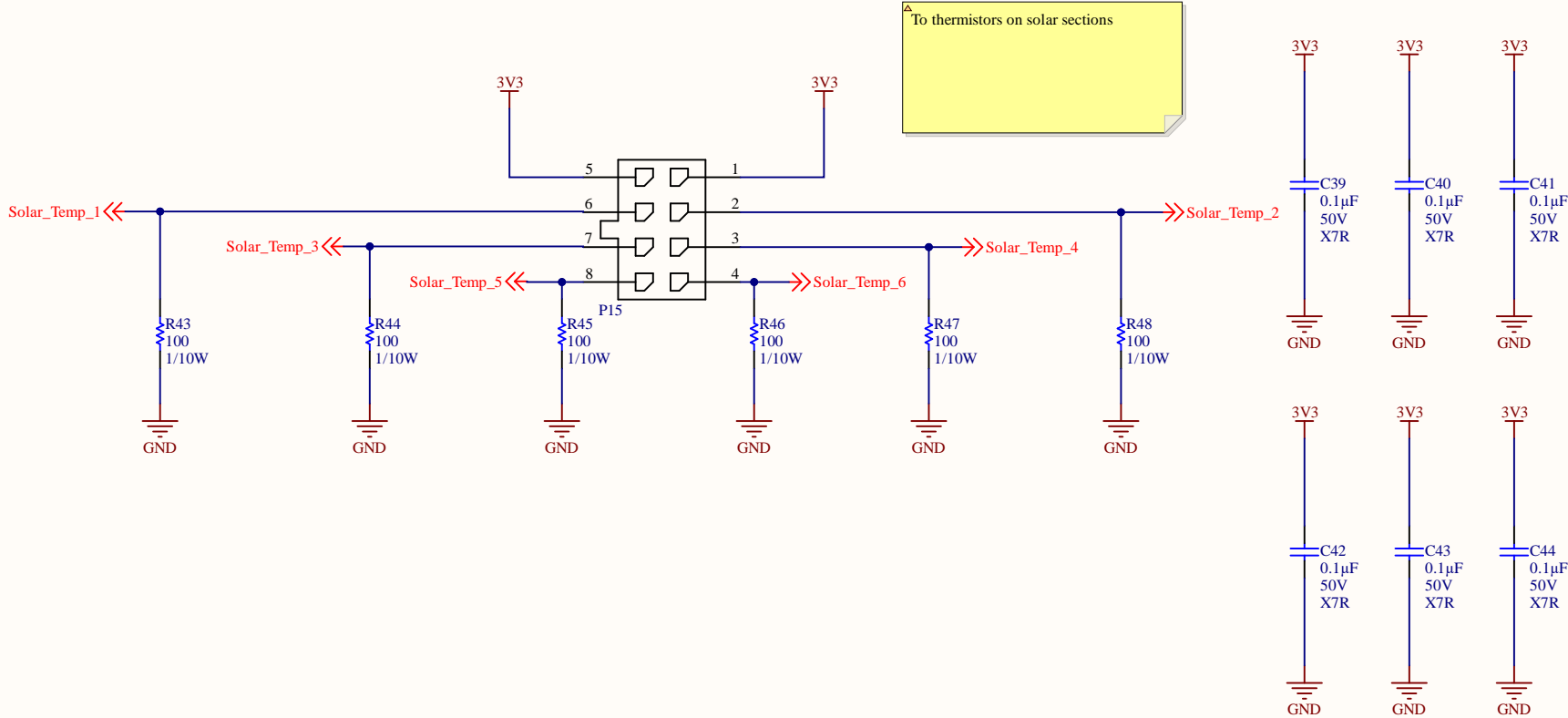
PROJECT		MSXIV_SolarSense.PrjPcb	
DOCUMENT		*	
PART NUMBER		VARIANT	[No Variations]
DRAWN BY		REVISION	1.0
LAST MODIFIED		SHEET	* OF *
			2020-02-23

MIDNIGHT

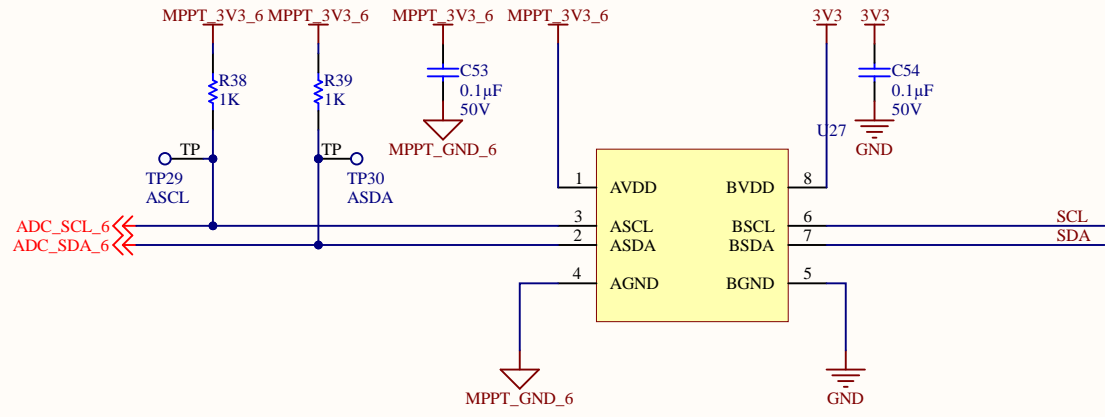
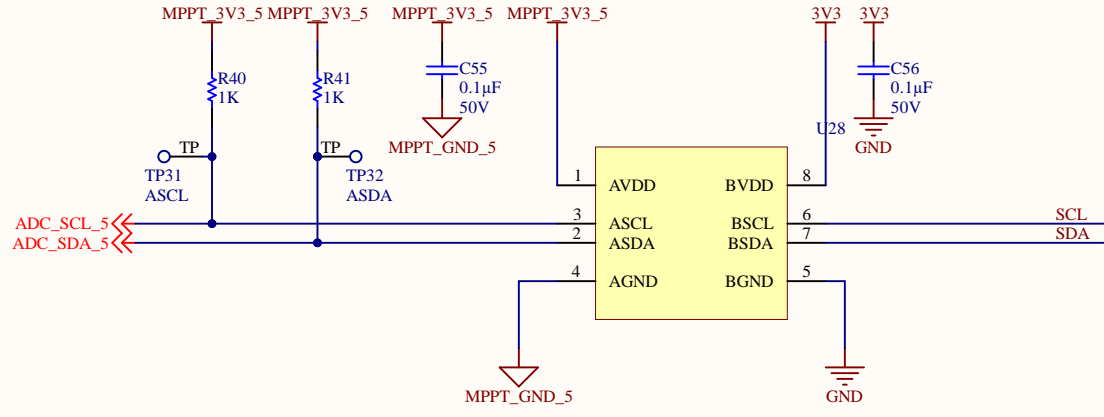
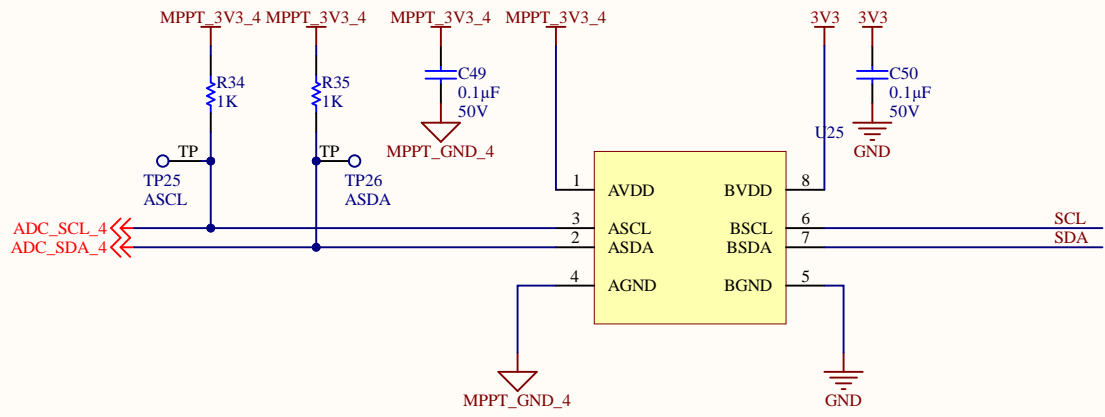
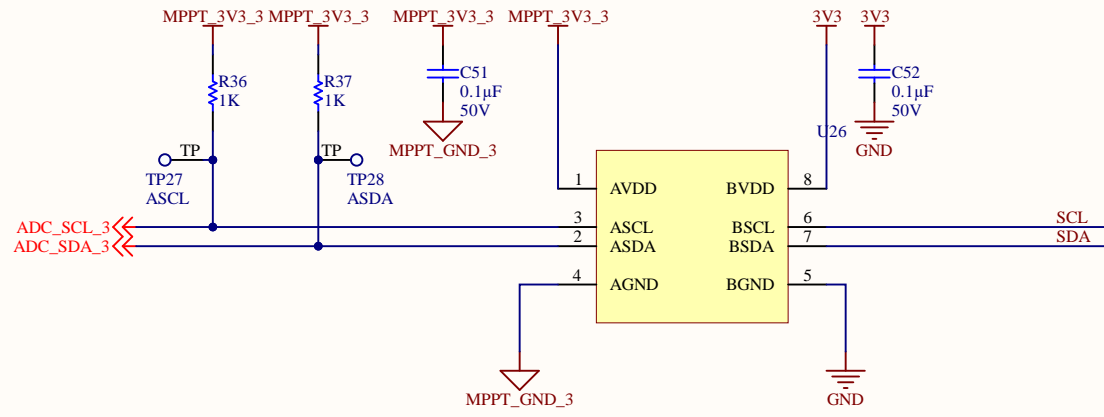
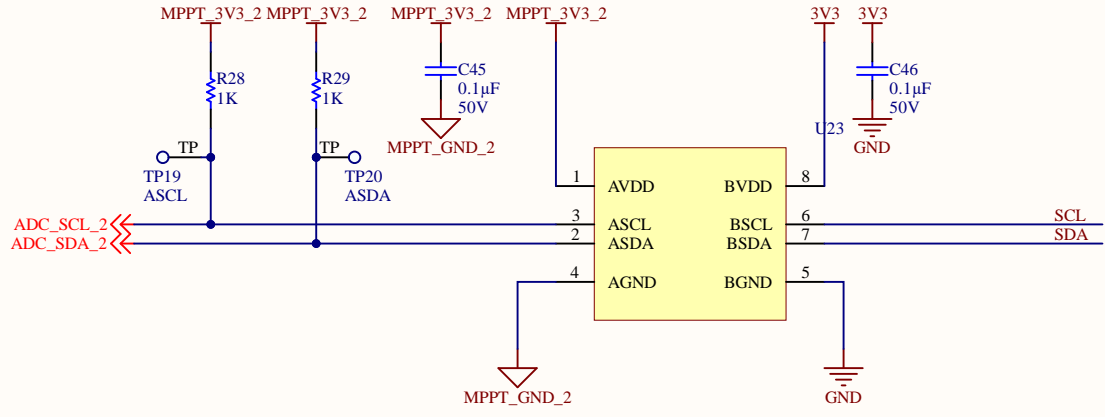
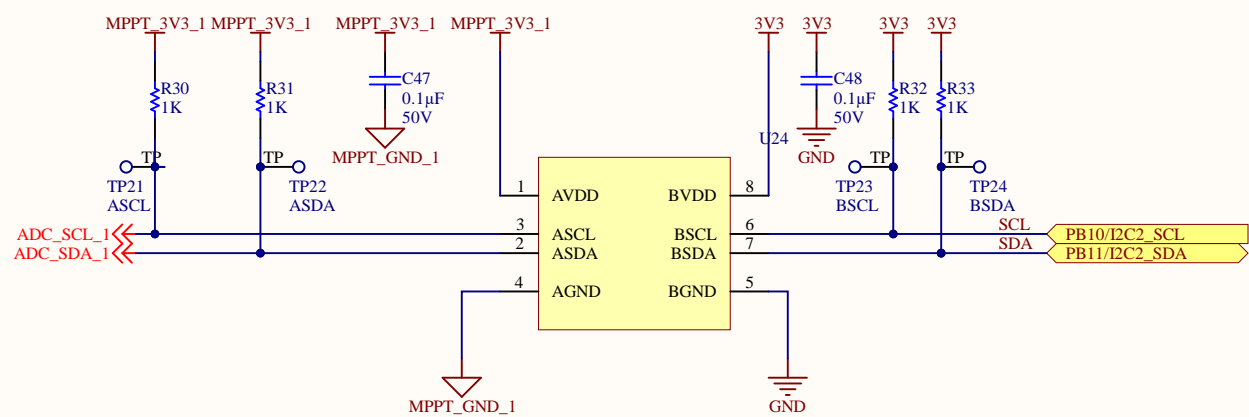
SUN

Engineering 5 - 1002
University of Waterloo
(519) 888-4567 x32978
hardware@uwmidsun.com

Temperature Sense for Array Sections



I2C Isolators for V-Sense



PROJECT		MSXIV_SolarSense.PrjPcb	
DOCUMENT		*	
PART NUMBER	VARIANT	[No Variations]	
DRAWN BY	REVISION	Aashmika Mali 1.0	
LAST MODIFIED	SHEET	2020-02-23 * OF *	

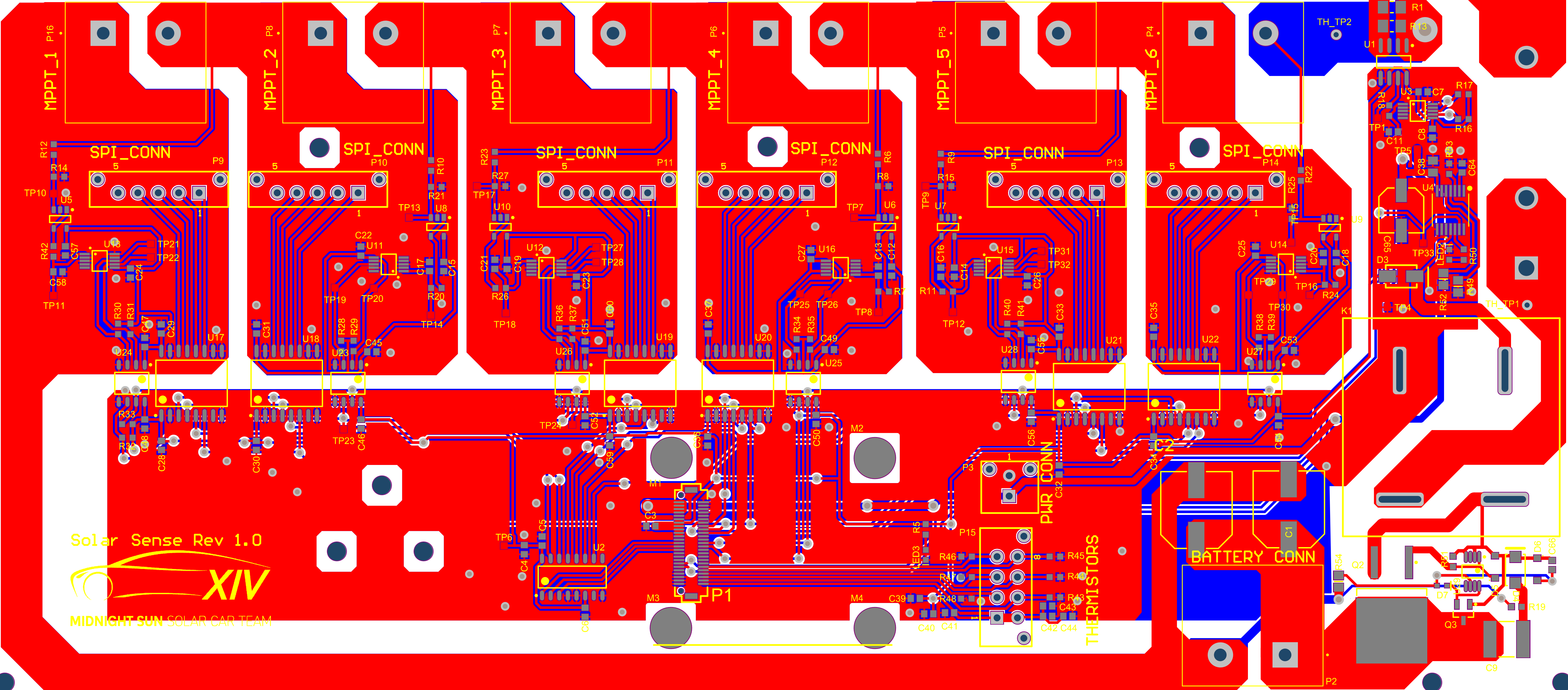
MIDNIGHT

SUN

Engineering 5 - 1002
University of Waterloo
(519) 888-4567 x32978
hardware@uwmidsun.com

[illegible]

MPPT_OUT_- MPPT_OUT_+ MPPT_OUT_- MPPT_OUT_+ MPPT_OUT_- MPPT_OUT_+ MPPT_OUT_- MPPT_OUT_+ MPPT_OUT_- MPPT_OUT_+



Solar Sense Rev 1.0



MIDNIGHT SUN SOLAR CAR TEAM

THERMISTORS

BATTERY CONN

PWR CONN

SPI_CONN

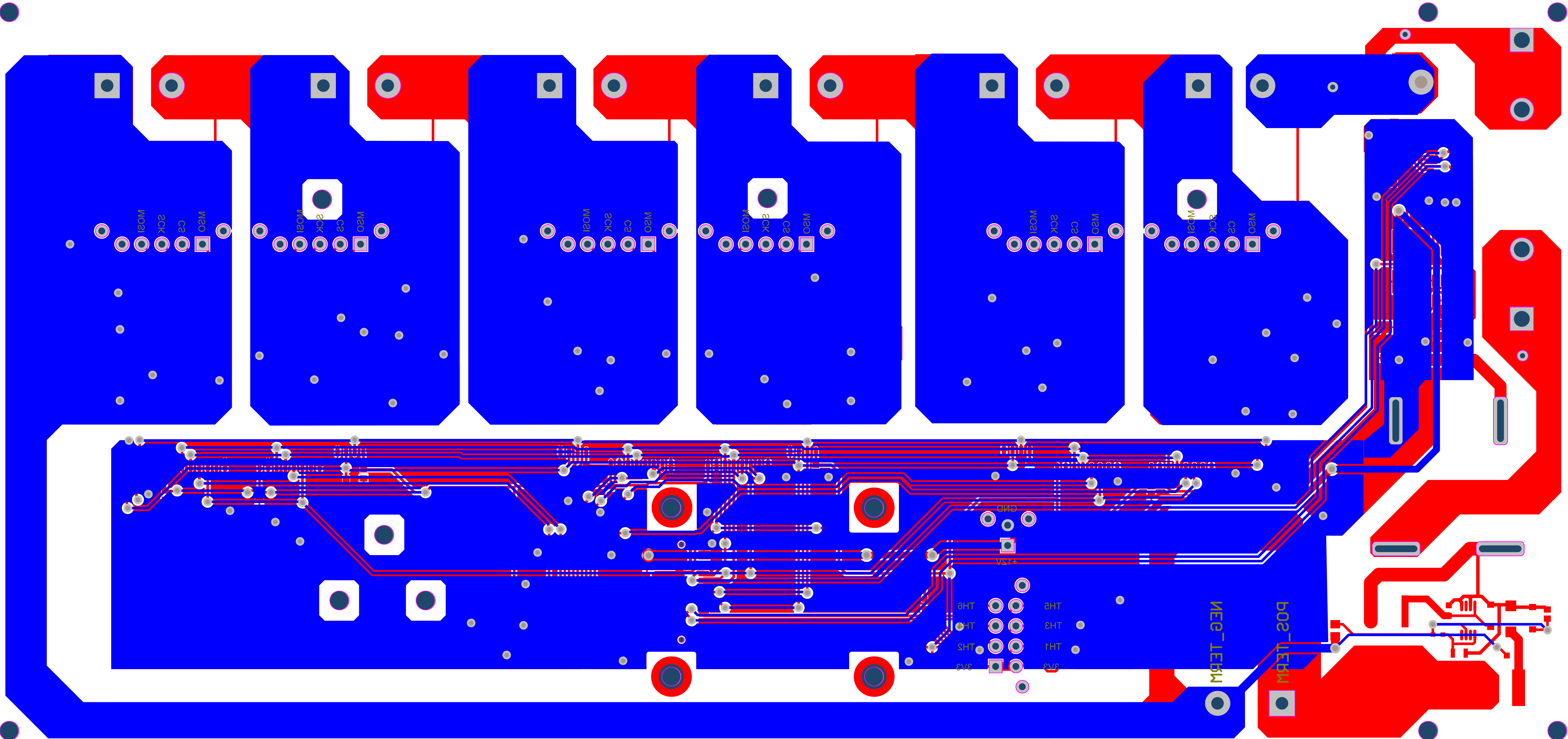
SPI_CONN

SPI_CONN

SPI_CONN

SPI_CONN

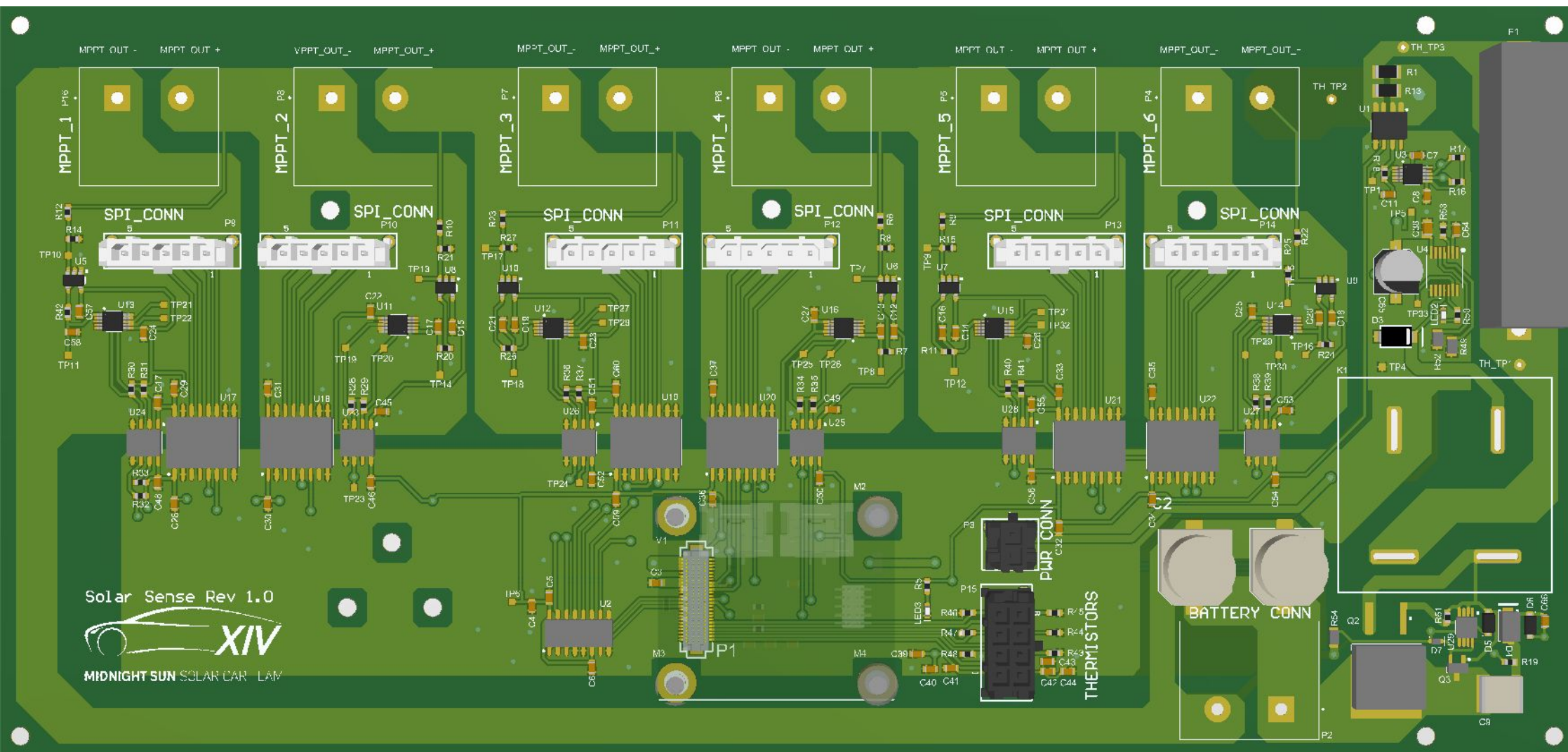
SPI_CONN



Solar Sense Rev 1.0



MIDNIGHT SUN SOLAR CAR LAM



Electrical Rules Check Report

[illegible]

Class	Document	Message
Warning	ADCs.SchDoc	Off grid Pin U13-3 at 3108.11mil,7194.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-4 at 1658.11mil,7694.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-5 at 1658.11mil,7544.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-6 at 3108.11mil,8044.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-7 at 3108.11mil,7544.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-8 at 3108.11mil,7694.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-9 at 1658.11mil,7194.41mil
Warning	ADCs.SchDoc	Off grid Pin U13-10 at 1658.11mil,7344.41mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-1 at 6774.41mil,7051.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-2 at 6774.41mil,5851.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-3 at 6774.41mil,6851.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-4 at 6774.41mil,6651.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-5 at 6774.41mil,6451.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-6 at 6774.41mil,6251.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-7 at 6774.41mil,6051.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-8 at 6774.41mil,5651.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-9 at 8574.41mil,5651.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-10 at 8574.41mil,6051.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-11 at 8574.41mil,6251.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-12 at 8574.41mil,6451.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-13 at 8574.41mil,6651.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-14 at 8574.41mil,6851.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-15 at 8574.41mil,5851.811mil
Warning	SPI_Interface.SchDoc	Off grid Pin U18-16 at 8574.41mil,7051.811mil
Warning	TemperatureSense.SchDoc	Off grid Power Object 3V3 at 4099.606mil,5389.764mil
Warning	TemperatureSense.SchDoc	Off grid Power Object 3V3 at 5899.606mil,5389.764mil
Warning	SPI_Interface.SchDoc	Off grid Power Object 3V3 at 6174.41mil,7351.811mil
Warning	SPI_Interface.SchDoc	Off grid Power Object GND at 6774.41mil,5351.811mil
Warning	ADCs.SchDoc	Off grid Power Object MPPT_3V3_1 at 3218.11mil,8674.41mil
Warning	ADCs.SchDoc	Off grid Power Object MPPT_3V3_1 at 3818.11mil,8674.41mil
Warning	SPI_Interface.SchDoc	Off grid Power Object MPPT_3V3_2 at 9074.41mil,7351.811mil
Warning	ADCs.SchDoc	Off grid Power Object MPPT_GND_1 at 818.11mil,7074.41mil
Warning	ADCs.SchDoc	Off grid Power Object MPPT_GND_1 at 3468.11mil,7074.41mil
Warning	ADCs.SchDoc	Off grid Power Object MPPT_GND_1 at 3818.11mil,8374.41mil
Warning	SPI_Interface.SchDoc	Off grid Power Object MPPT_GND_2 at 8574.41mil,5351.811mil
Warning	Controller_Board_Interface.SchDoc	Off grid Solar Sense Rev 1.0 at 4505.679mil,2561.84mil
Warning	ADCs.SchDoc	Off grid U13 at 1958.11mil,8194.41mil
Warning	SPI_Interface.SchDoc	Off grid U18 at 7474.41mil,6651.811mil

Design Rules Verification Report

Filename : C:\Users\Aashmika Mali\Documents\First Year\Midnight Sun\hardware\MSXIV_

Warnings 0
Rule Violations 159

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=10mil) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=10mil) (Max=80mil) (Preferred=15mil) (All)	0
Power Plane Connect Rule(Direct Connect)(Expansion=20mil) (Conductor Width=10mil) (Air Gap=10mil) (Entries=4,	0
Hole Size Constraint (Min=1mil) (Max=100mil) (All)	24
Hole To Hole Clearance (Gap=10mil) (All),(All)	4
Minimum Solder Mask Sliver (Gap=10mil) (All),(All)	29
Silk To Solder Mask (Clearance=10mil) (IsPad),(All)	85
Silk to Silk (Clearance=10mil) (All),(All)	17
Net Antennae (Tolerance=0mil) (All)	0
Height Constraint (Min=0mil) (Max=1000mil) (Preferred=500mil) (All)	0
Total	159

Hole Size Constraint (Min=1mil) (Max=100mil) (All)	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-118.111mil,118.11mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-118.111mil,4306.39mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-2218.858mil,3215.5mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-4099.52mil,1418.004mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-4099.52mil,433.752mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-4720.984mil,3221.5mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-5280.622mil,1418.004mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-5280.622mil,433.752mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-6713.063mil,877.5mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-6954.677mil,1260.104mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-7215.393mil,877.5mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-7316.102mil,3215.5mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-871.173mil,118.11mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-871.173mil,4306.39mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-9138.89mil,118.11mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (106.299mil > 100mil) Pad Free-(-9138.89mil,4306.39mil) on Multi-Layer Actual Hole Size = 106.299mil	
Hole Size Constraint: (248.031mil > 100mil) Pad K1-1(-451mil,1179mil) on Multi-Layer Actual Slot Hole Height = 248.031mil	
Hole Size Constraint: (248.031mil > 100mil) Pad K1-2(-1057.299mil,1179mil) on Multi-Layer Actual Slot Hole Height = 248.031mi	
Hole Size Constraint: (248.031mil > 100mil) Pad K1-3(-449.031mil,1925.063mil) on Multi-Layer Actual Slot Hole Height = 248.031mi	
Hole Size Constraint: (248.031mil > 100mil) Pad K1-4(-1059.268mil,1925.063mil) on Multi-Layer Actual Slot Hole Height = 248.031mil	
Hole Size Constraint: (145.669mil > 100mil) Pad M1-(-5277.468mil,1419.409mil) on Multi-Layer Actual Hole Size = 145.669mil	
Hole Size Constraint: (145.669mil > 100mil) Pad M2-(-4099.52mil,1418.004mil) on Multi-Layer Actual Hole Size = 145.669mil	
Hole Size Constraint: (145.669mil > 100mil) Pad M3-(-5280.622mil,433.752mil) on Multi-Layer Actual Hole Size = 145.669mil	
Hole Size Constraint: (145.669mil > 100mil) Pad M4-(-4099.52mil,433.752mil) on Multi-Layer Actual Hole Size = 145.669mil	

Hole To Hole Clearance (Gap=10mil) (All),(All)	
Hole To Hole Clearance Constraint: (Collision < 10mil) Between Pad Free-(-4099.52mil,1418.004mil) on Multi-Layer And Pad M2-(-4099.52mil,1418.004mil)	
M2-(-4099.52mil,1418.004mil) Constraint: (Collision < 10mil) Between Pad Free-(-4099.52mil,433.752mil) on Multi-Layer And Pad M4-(-4099.52mil,433.752mil)	
Hole To Hole Clearance Constraint: (Collision < 10mil) Between Pad Free-(-5280.622mil,1418.004mil) on Multi-Layer And Pad M3-(-5280.622mil,433.752mil)	
M3-(-5280.622mil,433.752mil) Constraint: (Collision < 10mil) Between Pad Free-(-5280.622mil,433.752mil) on Multi-Layer And Pad M4-(-4099.52mil,433.752mil)	
Minimum Solder Mask Sliver (Gap=10mil) (All),(All)	
Minimum Solder Mask Sliver Constraint: (6.727mil < 10mil) Between Pad C43-1(-3124.984mil,560.773mil) on Top Layer And Pad C43-2(-3071.834mil,560.773mil)	
Minimum Solder Mask Sliver Constraint: (6.727mil < 10mil) Between Pad C43-2(-3071.834mil,560.773mil) on Top Layer And Pad C43-3(-3071.834mil,560.773mil)	
Minimum Solder Mask Sliver Constraint: (8.198mil < 10mil) Between Pad C43-2(-3071.834mil,560.773mil) on Top Layer And Pad C43-3(-3071.834mil,560.773mil)	
Minimum Solder Mask Sliver Constraint: (4.145mil < 10mil) Between Pad P1-(-5162.512mil,1232.964mil) on Top Layer And Pad P1-(-5162.512mil,618.791mil)	
Minimum Solder Mask Sliver Constraint: (4.145mil < 10mil) Between Pad P1-(-5162.512mil,618.791mil) on Top Layer And Pad U10-1(-6229.441mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U10-1(-6229.441mil,2810.72mil) on Top Layer And Pad U10-2(-6266.842mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U10-2(-6266.842mil,2810.72mil) on Top Layer And Pad U4-1(-687.728mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-1(-687.728mil,2965.255mil) on Top Layer And Pad U4-10(-790.09mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-10(-790.09mil,2743.255mil) on Top Layer And Pad U4-10(-790.09mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-10(-790.09mil,2743.255mil) on Top Layer And Pad U4-11(-764.5mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-11(-764.5mil,2743.255mil) on Top Layer And Pad U4-12(-738.909mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-12(-738.909mil,2743.255mil) on Top Layer And Pad U4-13(-713.319mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-13(-713.319mil,2743.255mil) on Top Layer And Pad U4-2(-713.319mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-2(-713.319mil,2965.255mil) on Top Layer And Pad U4-3(-738.909mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-3(-738.909mil,2965.255mil) on Top Layer And Pad U4-4(-764.5mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-4(-764.5mil,2965.255mil) on Top Layer And Pad U4-5(-790.09mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-5(-790.09mil,2965.255mil) on Top Layer And Pad U4-6(-815.681mil,2965.255mil)	
Minimum Solder Mask Sliver Constraint: (3.59mil < 10mil) Between Pad U4-6(-815.681mil,2965.255mil) on Top Layer And Pad U4-8(-841.271mil,2743.255mil)	
Minimum Solder Mask Sliver Constraint: (3.591mil < 10mil) Between Pad U4-8(-841.271mil,2743.255mil) on Top Layer And Pad U5-1(-8780.031mil,2856.232mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U5-1(-8780.031mil,2856.232mil) on Top Layer And Pad U5-2(-8817.433mil,2856.232mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U5-2(-8817.433mil,2856.232mil) on Top Layer And Pad U6-1(-4003.063mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U6-1(-4003.063mil,2810.72mil) on Top Layer And Pad U6-2(-4040.464mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U6-2(-4040.464mil,2810.72mil) on Top Layer And Pad U7-1(-3637.905mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U7-1(-3637.905mil,2810.72mil) on Top Layer And Pad U7-2(-3675.307mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U7-2(-3675.307mil,2810.72mil) on Top Layer And Pad U8-1(-6595.386mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U8-1(-6595.386mil,2810.72mil) on Top Layer And Pad U8-2(-6632.787mil,2810.72mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U8-2(-6632.787mil,2810.72mil) on Top Layer And Pad U9-1(-1426.291mil,2805.799mil)	
Minimum Solder Mask Sliver Constraint: (5.78mil < 10mil) Between Pad U9-1(-1426.291mil,2805.799mil) on Top Layer And Pad U9-2(-1463.693mil,2805.799mil)	
Minimum Solder Mask Sliver Constraint: (5.779mil < 10mil) Between Pad U9-2(-1463.693mil,2805.799mil) on Top Layer And Pad U9-2(-1463.693mil,2805.799mil)	

Silk To Solder Mask (Clearance=10mil) (IsPad),(All)

Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Arc (-230.11mil,851.756mil) on Top Overlay And Pad D6-1(-262mil,838.37mil) or
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Arc (-538.89mil,710.244mil) on Top Overlay And Pad D5-1(-507mil,723.63mil) or
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Arc (-853.37mil,702.622mil) on Top Overlay And Pad D7-1(-843.528mil,679mil) or
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad C1-1(-1701mil,947.772mil) on Top Layer And Text "BATT ERY CONN"
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad C1-1(-1701mil,947.772mil) on Top Layer And Text "C1"
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C1-1(-1701mil,947.772mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C1-1(-1701mil,947.772mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.709mil < 10mil) Between Pad C11-2(-1121.575mil,3308mil) on Top Layer And Text "TP1"
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C1-2(-1701mil,1294.228mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C1-2(-1701mil,1294.228mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.995mil < 10mil) Between Pad C15-1(-6595.386mil,2553.24mil) on Top Layer And Text "C15"
Silk To Solder Mask Clearance Constraint: (7.941mil < 10mil) Between Pad C15-2(-6595.386mil,2500.09mil) on Top Layer And Text "C15"
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad C2-1(-2236mil,943.772mil) on Top Layer And Text "BATT ERY CONN"
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C2-1(-2236mil,943.772mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C2-1(-2236mil,943.772mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C2-2(-2236mil,1290.228mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C2-2(-2236mil,1290.228mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad C34-1(-2483.181mil,1543.004mil) on Top Layer And Text "C2"
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad C34-2(-2483.181mil,1489.854mil) on Top Layer And Text "C2"
Silk To Solder Mask Clearance Constraint: (9.475mil < 10mil) Between Pad C6-2(-5776.488mil,498.713mil) on Top Layer And Text "C6"
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C65-1(-1049.5mil,2968.334mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C65-1(-1049.5mil,2968.334mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C65-2(-1049.5mil,2736.05mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad C65-2(-1049.5mil,2736.05mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (6.535mil < 10mil) Between Pad D3-1(-1130.008mil,2470.294mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (6.535mil < 10mil) Between Pad D3-1(-1130.008mil,2470.294mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (6.535mil < 10mil) Between Pad D3-2(-972.527mil,2470.294mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (6.535mil < 10mil) Between Pad D3-2(-972.527mil,2470.294mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (2.839mil < 10mil) Between Pad D7-2(-784.472mil,679mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.213mil < 10mil) Between Pad LED2-2(-772.301mil,2626.291mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.213mil < 10mil) Between Pad LED3-2(-3804.244mil,827.453mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.408mil < 10mil) Between Pad M3(-5280.622mil,433.752mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.408mil < 10mil) Between Pad M4(-4099.52mil,433.752mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P10-0(-6969.598mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P10-0(-6969.598mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P10-0(-7678.26mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P10-0(-7678.26mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (8.78mil < 10mil) Between Pad P1-1(-5091.646mil,1162.097mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P11-0(-5292.433mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P11-0(-5292.433mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P11-0(-6001.094mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P11-0(-6001.094mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P12-0(-4371.173mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P12-0(-4371.173mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P12-0(-5079.834mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P12-0(-5079.834mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (8.767mil < 10mil) Between Pad P1-25(-5091.646mil,689.657mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (9.4mil < 10mil) Between Pad P1-26(-5233.378mil,689.657mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P13-0(-2691.055mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P13-0(-2691.055mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P13-0(-3399.716mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P13-0(-3399.716mil,3031.39mil) on Multi-Layer And Track

Silk To Solder Mask (Clearance=10mil) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P14-0(-1772.748mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P14-0(-1772.748mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P14-0(-2481.409mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P14-0(-2481.409mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P15-0(-3235.74mil,374.697mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.376mil < 10mil) Between Pad P15-0(-3235.74mil,374.697mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P15-0(-3235.74mil,965.248mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.918mil < 10mil) Between Pad P15-0(-3235.74mil,965.248mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.401mil < 10mil) Between Pad P1-50(-5233.378mil,1162.097mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P3-0(-3198.89mil,1353.118mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P3-0(-3198.89mil,1353.118mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P3-0(-3435.11mil,1353.118mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P3-0(-3435.11mil,1353.118mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (8.4mil < 10mil) Between Pad P9-0(-7890.858mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P9-0(-7890.858mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (7.053mil < 10mil) Between Pad P9-0(-8599.519mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.281mil < 10mil) Between Pad P9-0(-8599.519mil,3031.39mil) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (9.133mil < 10mil) Between Pad R18-1(-1119mil,3460.512mil) on Top Layer And Text "R18"
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad R25-1(-1684.549mil,2803.988mil) on Top Layer And Text "TP15"
Silk To Solder Mask Clearance Constraint: (Collision < 10mil) Between Pad R25-2(-1684.549mil,2865.012mil) on Top Layer And Text "TP15"
Silk To Solder Mask Clearance Constraint: (2.51mil < 10mil) Between Pad R28-2(-7190.071mil,2037.098mil) on Top Layer And Text "U23"
Silk To Solder Mask Clearance Constraint: (9.584mil < 10mil) Between Pad R38-2(-1875.11mil,2056.783mil) on Top Layer And Text "U27"
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad R49-1(-720.701mil,2376.449mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.513mil < 10mil) Between Pad R49-2(-720.701mil,2447.315mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad R52-1(-805.611mil,2419.175mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.513mil < 10mil) Between Pad R52-2(-805.611mil,2490.041mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (8.806mil < 10mil) Between Pad R54-1(-1413.039mil,738.755mil) on Top Layer And Text "R54"
Silk To Solder Mask Clearance Constraint: (8.513mil < 10mil) Between Pad R54-1(-1413.039mil,738.755mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (7.874mil < 10mil) Between Pad R54-2(-1413.039mil,667.889mil) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (6.54mil < 10mil) Between Pad TP15-TP(-1687.063mil,2667.961mil) on Top Layer And Text "U14"
Silk To Solder Mask Clearance Constraint: (9.791mil < 10mil) Between Pad U13-1(-8675.173mil,2599.106mil) on Top Layer And Text "C57"
Silk To Solder Mask Clearance Constraint: (9.797mil < 10mil) Between Pad U13-2(-8675.173mil,2579.421mil) on Top Layer And Text "C57"
Silk To Solder Mask Clearance Constraint: (8.009mil < 10mil) Between Pad U4-(-654mil,2980.505mil) on Top Overlay And Polygon Region (42 hole(s))
Top
Silk to Silk (Clearance=10mil) (All),(All)
Silk To Silk Clearance Constraint: (3.858mil < 10mil) Between Text "1" (-3324.874mil,1410.598mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.806mil < 10mil) Between Text "1" (-3536.527mil,496.744mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-2386.921mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-3305.228mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-4985.346mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-5906.606mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-7583.771mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "5" (-8505.031mil,3092.807mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.795mil < 10mil) Between Text "8" (-3174.323mil,855.012mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (8.189mil < 10mil) Between Text "BATT ERY CONN" (-2256.516mil,817.452mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (8.189mil < 10mil) Between Text "BATT ERY CONN" (-2256.516mil,817.452mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (9.475mil < 10mil) Between Text "C66" (-156.797mil,861.324mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (9.598mil < 10mil) Between Text "D3" (-1186.989mil,2548.283mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (9.598mil < 10mil) Between Text "D3" (-1186.989mil,2548.283mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (7.775mil < 10mil) Between Text "PWR CONN" (-3073.89mil,1045.52mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (8.737mil < 10mil) Between Text "PWR CONN" (-3073.89mil,1045.52mil) on Top Overlay And Track
Silk To Silk Clearance Constraint: (8.966mil < 10mil) Between Text "PWR CONN" (-3073.89mil,1045.52mil) on Top Overlay And Track